MSAPに最適なビアフィリング用硫酸銅めっき添加剤

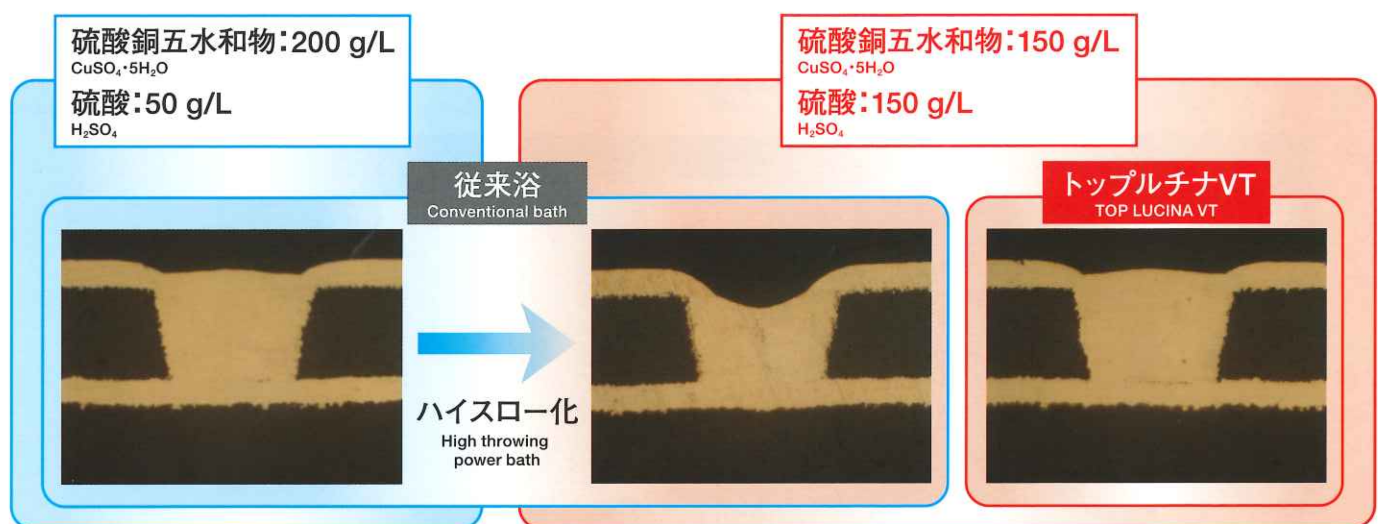
Acid Copper Plating Additives for Via-filling to be Suitable for MSAP

トップルチナVT

TOP LUCINA VT

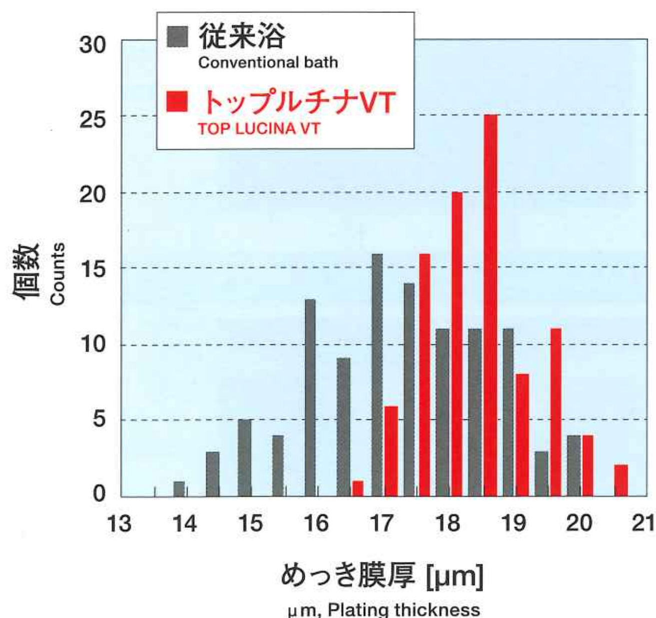
- 優れたビアフィリング性能と高いスルーホールめっき性能の両立が可能
- 浴組成のハイスロー化に対応することで良好な膜厚均一性を実現
- 全ての添加剤成分の定量分析が可能

- Can provide both an excellent via-filling performance and a high plating ability for through-holes
- Can provide a good uniformity of thickness by applying to bath composition to be applicable to high throwing power
- Quantitative analyses are available for all additives

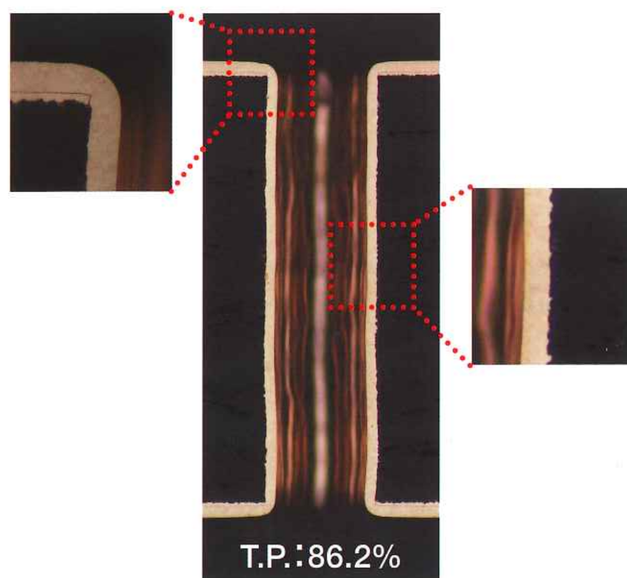


電流密度 2.0 A/dm² Current density　穴径 110μm Via diameter　ビア深さ 60μm Via depth

パターンめっきにおける膜厚分布
Distribution of thickness on a pattern plating



スルーホールめっき析出性
Deposition ability of through-hole



電流密度 2.0 A/dm² Current density　穴径 0.3 mm Via diameter　板厚 1.2mm Board thickness